Materials Declaration

Package	TSSOP_EP
Body Size	4.4 mm
LeadCount	24
Option	Halide-free, Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.9	3.41 E-02	344375
Epoxy & Phenol Resin	12.8	5.01 E-03	50640
Carbon black	0.3	1.22 E-04	1228
Subtotal		3.92 E-02	396243

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.20	4.20 E-02	424276
Ni	3.00	1.31 E-03	13233
Si	0.65	2.84 E-04	2871
Mg	0.15	6.50 E-05	657
Subtotal		4.36 E-02	441038

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.01 E-03	10190

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	3.67 E-03	37101

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.89 E-04	3933

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	9.25 E-03	93491

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	73.40	1.31 E-03	13215
Epoxy Resin	18.35	3.27 E-04	3304
Metal oxide	2.75	4.90 E-05	495
Curing and hardening agent	2.75	4.90 E-05	495
Gamma Butyrolactone	2.75	4.90 E-05	495
Subtotal		1.78 E-03	18005

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA3050B. ICP-AES.
Cd	Not Detected	EPA3050B. ICP-AES.
Hg	Not Detected	EPA 3052B. Mercury Analyser
Cr+6	Not Detected	EPA 7196A. UV-VIS.
PBB	Not Detected	EPA 1614. GC-MS.
PBDE	Not Detected	EPA 1614. GC-MS.

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	Draft IEC 62321. ICP-OES.
Cd	Not Detected	Draft IEC 62321. ICP-OES.
Hg	Not Detected	Draft IEC 62321. ICP-OES.
Cr+6	Not Detected	Draft IEC 62321. UV-VIS.
PBB	Not Detected	Draft IEC 62321. GC-MSD.
PBDE	Not Detected	Draft IEC 62321. GC-MSD.

Package Totals

Weight (g)	PPM
9.89 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES